



SOT403-1

plastic, thin shrink small outline package; 16 leads; 5 mm x 4.4 mm x 1.1 mm body

23 February 2018

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	TSSOP16
Package type industry code	TSSOP16
Package style descriptive code	TSSOP (thin shrink small outline package)
Package body material type	P (plastic)
JEDEC package outline code	MO-153
Mounting method type	S (surface mount)
Number of package outline detail graphic references	0
Issue date	18-2-2003
Manufacturer package code	SOT403

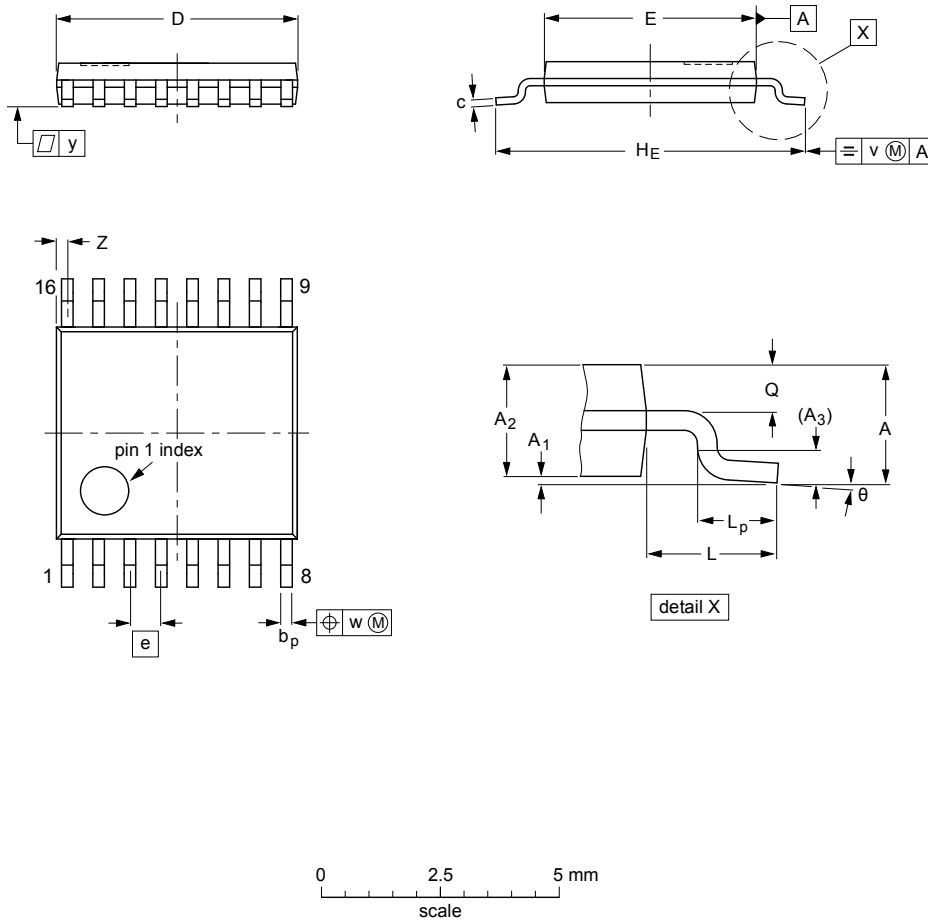
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	4.9	-	5	5.1	mm
E	package width	4.3	-	4.4	4.5	mm
A	seated height	-	-	1.1	1.1	mm
A ₂	package height	0.8	-	0.9	0.95	mm
e	nominal pitch	-	-	0.65	-	mm
n ₂	actual quantity of termination	-	-	16	-	

2. Package outline

TSSOP16: plastic thin shrink small outline package; 16 leads; body width 4.4 mm

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DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A ₁	A ₂	A ₃	b _p	c	D ⁽¹⁾	E ⁽²⁾	e	H _E	L	L _p	Q	v	w	y	Z ⁽¹⁾	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.40 0.06	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT403-1		MO-153				99-12-27 03-02-18

Fig. 1. Package outline TSSOP16 (SOT403-1)

3. Soldering

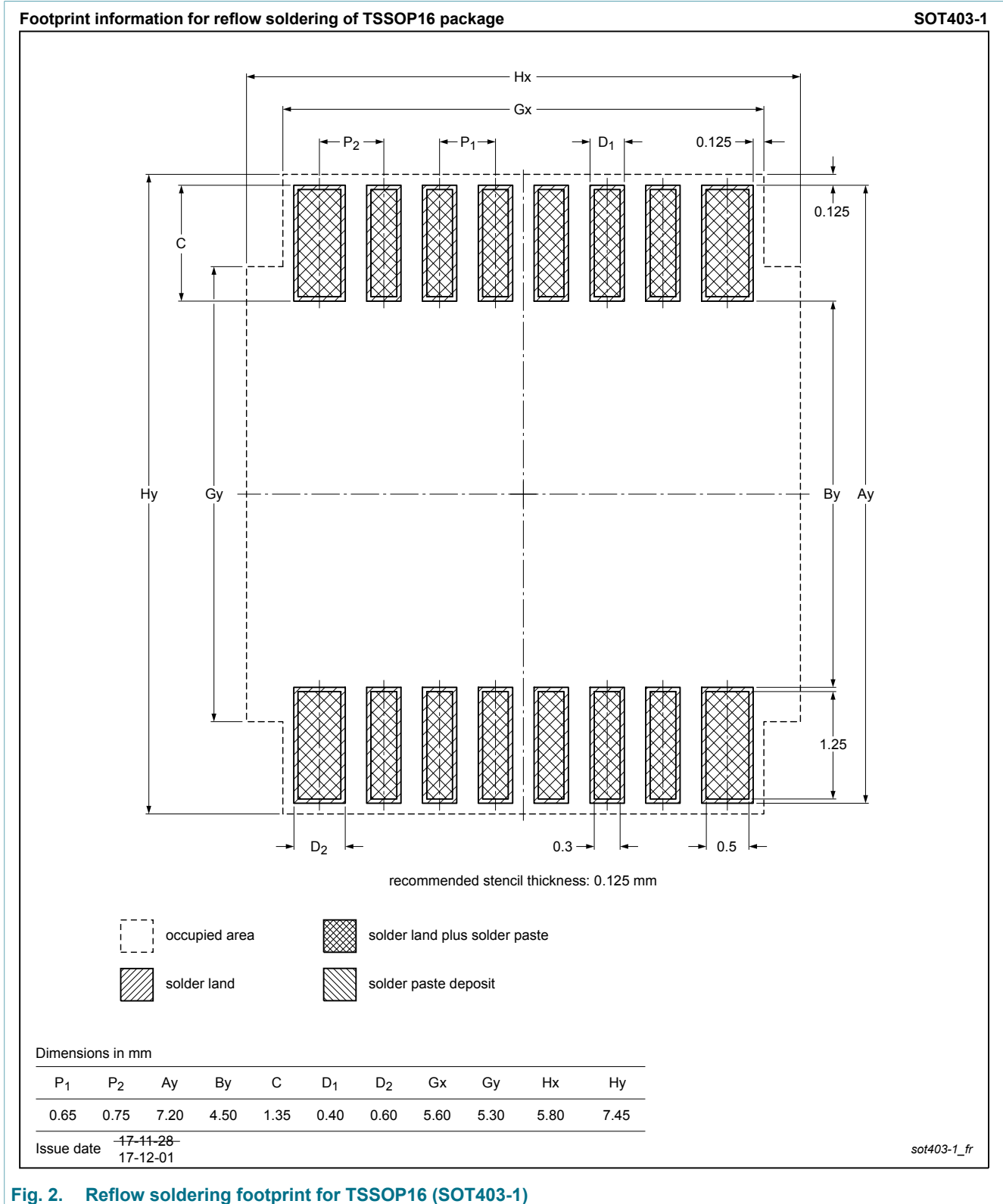


Fig. 2. Reflow soldering footprint for TSSOP16 (SOT403-1)

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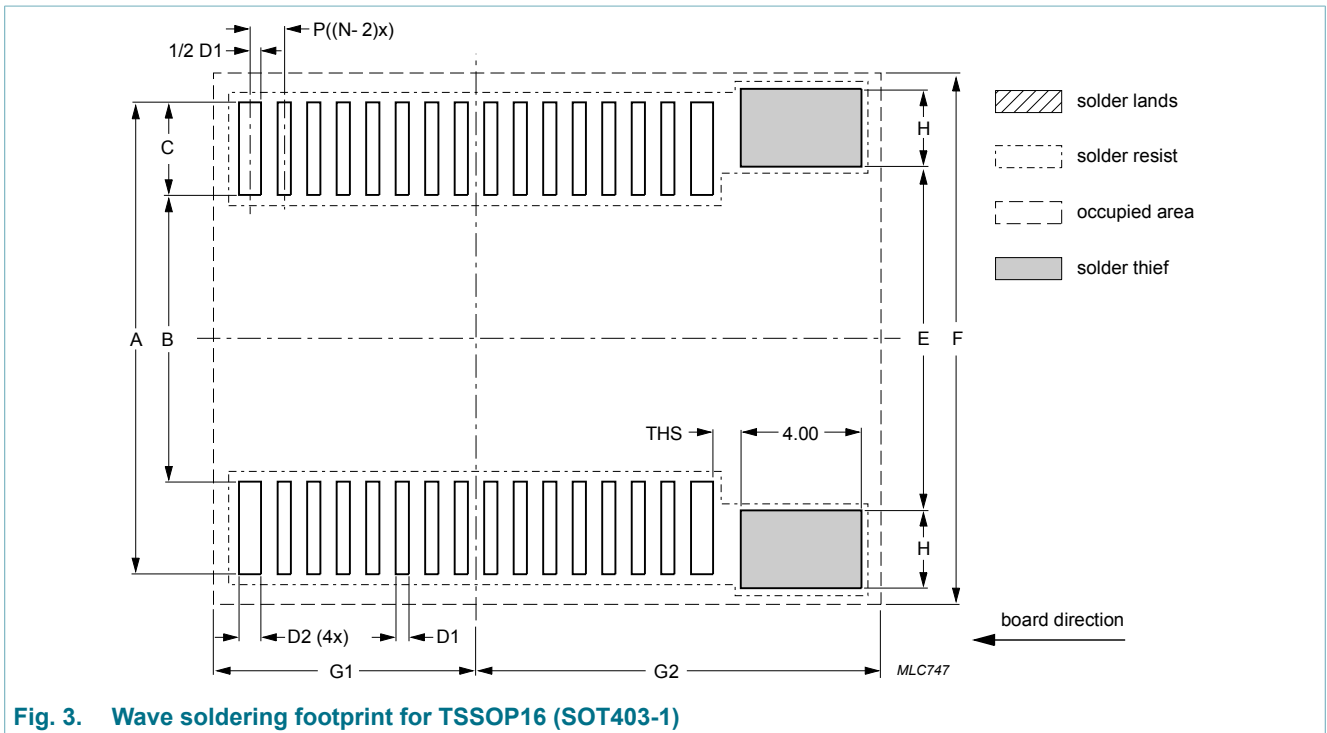


Fig. 3. Wave soldering footprint for TSSOP16 (SOT403-1)

4. Legal information

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